

## E2 Technical Specifications

Printer	E2		
Build Volume (W×D×H)	Single Extruder Print	Dual Extruder Print	
	330×240×240 mm	295×240×240 mm	
Machine Size (W×D×H)	607×596×465 mm		
Weight	Net Weight	Gross Weight (Carton Only)	Gross Weight (Carton with Pallet)
	35 Kg	41.3 Kg	50 Kg
Electrical	Power Supply Input	100-240 V AC, 50/60Hz 230 V @ 2A	
	Power Supply Output	24 V DC, 350 W	
General	Print Technology	FFF	
	Print Head System	IDEX Independent Dual Extruders	
	Filament Diameter	1.75 mm	
	XYZ Step Size	0.78125, 0.78125, 0.078125 micron	
	Print Head Travel Speed	30-150 mm/s	
	Build Plate	Flexible Steel Plate with BuildTak	
	Max Build Plate Temperature	110 °C	
	Heated Bed Material	Silicone	
	Build Plate Leveling	Mesh-leveling with Flatness Detection	
	Filament Run-out Sensor	Available	
	Supported Materials	PLA / ABS / HIPS / PC / TPU / TPE / NYLON / PETG / ASA / PP / PVA / Glass Fiber Infused / Carbon Fiber Infused / Metal Fill / Wood Fill	
	Layer Height	0.02 – 0.25 mm	
	Nozzle Diameter	0.4 mm (Default), 0.2/ 0.6/ 0.8/ 1.0 mm (Available)	
	Hot End	V3P	
	Max Nozzle Temperature	300 °C	
	Connectivity	Wi-Fi, LAN, USB port, Live camera	
	Noise Emission (Acoustic)	< 50 dB (A) when building	
	Operating Ambient Temperature	15-30 °C, 10-90% RH non-condensing	
	Storage Temperature	-25 to 55°C, 10-90% RH non-condensing	
	Filter	HEPA filter with activated charcoal	
Technical Certifications	CB, CE, FCC, RoHS, RCM		
Software	Slicing Software	ideaMaker	
	Supported File Types	STL/ OBJ/ 3MF/ OLTP	
	Supported OS	Windows/ macOS/ Linux	
	Machine Code Type	GCODE	
Printer Controller	User Interface	7-inch Touch Screen	
	Network	Wi-Fi, Ethernet	
	Power Loss Recovery	Available	
	Screen Resolution	1024×600	
	Motion Controller	Atmel ARM Cortex-M4 120MHZ FPU	
	Logic Controller	NXP ARM Cortex-A9 Quad 1 GHz	
	Memory	1 GB	
	Onboard Flash	8 GB	
	OS	Embedded Linux	
	Ports	USB 2.0×2, Ethernet×1	